

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	120	((yun with gi with kim).in. (yong with shik with park).in. (sung with joon with park).in.) and samsung.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:47
L6	0	(substrate ink chamber heat first second trench uniform (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
L7	0	(substrate ink chamber heat first second trench uniform (micron)).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
L8	0	(substrate ink chamber heat first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
L9	2	(substrate ink chamber first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51
L10	10	(substrate ink first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51
L11	8	10 not 9	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3742	347/54,56,61,65,67.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 13:28
L2	2200	((substrate) with (trench depth height)) same (micron and area)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 13:29
L3	56	1 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 13:29
S1	2	"20040155943"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/18 13:44
S2	2	"6158843".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:20
S3	3090	347/54,56,61,65,67.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:21
S4	14254	(ink liquid fluid) with ((supply passage path) with (trench depth height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:23
S5	350	S3 and S4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:23
S6	2810	(ink liquid fluid) with ((supply passage path) near3 (trench depth height))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:25
S7	964	347/65.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:23
S8	223	S4 and S7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:23

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S9	15	((ink liquid fluid) with ((supply passage path) near3 (trench depth height))) with (micron "um")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:27
S10	34	((ink liquid fluid) with ((supply passage path) near3 (trench depth height))) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:29
S11	11	S3 and S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:28
S12	198	((supply passage path) with (trench depth height)) same (micron and area)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:35
S13	64097	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:29
S14	14	S12 and S13	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:33
S15	1778	((substrate) with (trench depth height)) same (micron and area)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:35
S16	12	S3 and S15	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/28 13:35
S17	9	("3747120" "4275290" "4394670" "4438191" "4459600" "4463359" "4490728" "4535343" "4571599").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 13:39
S18	7	("4723129" "5278585" "5821962" "5841448" "5943074" "6109735" "6168264").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 13:41
S19	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 13:41
S20	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 14:31
S21	1	"4882595".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 14:31
S22	15	("4601777" "4612554" "4638337" "4789425" "4829324" "4851371" "4863560" "4875968" "4882595" "4899178" "4899181" "4961821" "5160577" "5308442" "Re32572").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 14:32
S23	54	("5387314").URPN.	USPAT	OR	ON	2005/11/28 14:40
S24	13	("4894664" "5387314" "5679593" "5682188" "5706041" "5773326" "5851412" "5852459" "5876497" "5971527" "6000787" "6033581" "6103099").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/28 14:41

EAST Search History

S25	79	("4882595").URPN.	USPAT	OR	ON	2006/05/11 10:04
S26	60	S25 and (height depth deep)	USPAT	OR	ON	2006/05/11 11:06
S27	39	S25 and (substrate with (height depth deep))	USPAT	OR	ON	2006/05/11 11:09
S28	37	(silicon with substrate with manifold) same (height depth thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:11
S29	1019	347/65.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:11
S30	5	S28 and S29	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:10
S31	74	(silicon same (substrate with manifold)) same (height depth thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:11
S32	14	S29 and S31	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:11
S33	66173	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:11
S34	42	S31 and S33	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 11:12
S35	13	(US-20040155943-\$).dld. or (US-6409317-\$ or US-6540337-\$ or US-4882595-\$ or US-4638337-\$ or US-6126276-\$ or US-6132033-\$ or US-6331055-\$ or US-6938340-\$ or US-6019457-\$ or US-5387314-\$ or US-4275290-\$ or US-6003986-\$).dld.	US-PGPUB; USPAT	OR	ON	2006/05/11 12:59
S36	3379	347/54,56,61,62,65.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:01
S37	18967	(substrate manifold) with ((depth height) same ("5" "20"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:10
S38	117	S36 and S37	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:02

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S39	76726	(substrate manifold) with ((depth height thickness) same ("5" "20"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:11
S40	10018	(substrate manifold) with silicon with ((depth height thickness) same ("5" "20"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:10
S41	9139	(substrate manifold) with silicon with ((depth height thickness) with ("5" "20"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:10
S42	62602	(substrate manifold) with ((depth height thickness) with ("5" "20"))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:11
S43	68	S36 and S41	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 13:11
S44	459	((support with substrate) with (thick\$4 height depth)) same ("5" and "20")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:30
S45	2298	347/61-65.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:30
S46	0	S44 and S45	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:29
S47	66173	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:18
S48	11	S44 and S47	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:30
S49	702	((support with substrate) with (thick\$4 height depth)) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:33
S50	9	S45 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:30

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S51	18	S47 and S49	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:30
S52	28	((support with substrate) same manifold same (thick\$4 height depth) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:34
S53	0	S47 and S52	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:34
S54	18	((ink liquid fluid) with manifold with substrate) same (thick\$4 height depth) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:02
S55	8	S47 and S54	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 14:35
S56	201	((ink liquid fluid) with manifold) same (thick\$4 height depth) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:06
S57	43	S47 and S56	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:02
S58	38	((ink liquid fluid) with manifold) same (step trench) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:07
S59	4	S47 and S58	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:06
S60	774	((ink liquid fluid) with substrate) same (step trench) same (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:07
S61	22	S45 and S60	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:10
S62	743	(print\$3head near4 (dimension geometry))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:11

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S63	125	S45 and S62	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:12
S64	388	(print\$3head near4 (dimension geometry)) and (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:18
S65	86	S45 and S64	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:12
S66	255	(print\$3head with (dimension geometry)) and ((micron micro\$2meter) with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:17
S67	62	S45 and S66	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:16
S68	44	S47 and S66 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:16
S69	58	S66 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:18
S70	1019	"347"/65.ccis.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:18
S71	325	S70 and (micron micro\$2meter)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:18
S72	312	S71 and (height depth thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:25
S73	264	S71 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:19
S74	6129	manifold with (height depth thickness)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:25

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S75	77	S45 and S74	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/11 15:26
S76	2	("4528070" "5126768").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/11 15:31
S77	286	((etch\$3 near3 depth) with (micron micro\$2meter)) same (channel manifold)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:44
S78	3261	347/54,56,61,65,67.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:42
S79	66173	"347"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:42
S80	96	S77 and S78	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:42
S81	166	((etch\$3 near3 depth) with (micron micro\$2meter)) same (silicon with substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:44
S82	7	S79 and S81	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 08:44
S83	1907	((supply flow) near4 channel) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 09:04
S84	91	S78 and S83	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 09:07
S85	17	S84 not silverbrook.in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 09:08
S86	12	("4882595" "4897674" "5412413" "5463413" "5988786" "6158843" "6231168" "6309054" "6364467" "6409318" "6439692" "6682177").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:11
S87	12	("4882595" "4897674" "5412413" "5463413" "5988786" "6158843" "6231168" "6309054" "6364467" "6409318" "6439692" "6682177").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:24
S88	1	"5308442".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:24

EAST Search History

S89	14	("4601777" "4612554" "4638337" "4789425" "4829324" "4851371" "4863560" "4875968" "4882595" "4899178" "4899181" "5131978" "5141596" "Re32572").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:28
S90	57	("5308442").URPN.	USPAT	OR	ON	2006/05/12 09:31
S91	3	("4882595" "5198834" "5308442").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:32
S92	9	("4615756" "4966646" "5308442" "5385633" "5387314" "5441593" "5658471" "6209993" "6309056").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:34
S93	17	("4601777" "4612554" "4638337" "4789425" "4808260" "4829324" "4851371" "4863560" "4875968" "4882595" "4899178" "4899181" "4961821" "5160577" "5277754" "5308442" "Re32572").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:38
S94	5	("5308442" "5371531" "5387314" "5402162" "5463412").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 09:58
S95	2	("6412921").URPN.	USPAT	OR	ON	2006/05/12 09:59
S96	23	("4500895" "4771295" "4877745" "5278584" "5305015" "5449754" "5474796" "5658802" "5681757" "5700637" "5719605" "5874554" "5900892" "5958342" "6155675" "6155676" "6183067" "6221653" "6228659" "6242266" "6250738" "6290331" "6412921").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 10:00
S97	2967	(substrate same trench) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:53
S98	26	S78 and S97	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 10:30
S99	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 10:39
S10 0	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 11:15
S10 1	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 11:15
S10 2	21	("20010003460" "5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/12 11:19
S10 3	2	"6412921".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:21
S10 4	1	2000-117143.NRAN.	DERWENT	OR	ON	2006/05/12 11:19
S10 5	2	"5317346".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:11
S10 6	1	10/747204	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:27

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S10 7	1	jp-04010940-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:27
S10 8	3170	(substrate same (shelf trench)) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:12
S10 9	56	S79 and S108	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:57
S11 0	204	(die same (shelf trench)) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 11:57
S11 1	3	S79 and S110	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:09
S11 2	2	ep-401996-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:10
S11 3	2	ep-764533-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:10
S11 4	2	ep-771658-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:11
S11 5	2	"5308442".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:11
S11 6	2	ep-401996-\$ did.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:11
S11 7	283	(substrate same (shelf trench) near4 ("5" "20")) same micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:13
S11 8	6	S79 and S117	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:13

EAST Search History

S11 9	1	"6540337".pn. and micron	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/12 12:15
S12 0	10	(US-20040155943-\$).did. or (US-4882595-\$ or US-6896360-\$ or US-6561632-\$ or US-5387314-\$ or US-6540337-\$ or US-6003986-\$ or US-6682177-\$ or US-6412921-\$ or US-5317346-\$).did.	US-PGPUB; USPAT	OR	ON	2006/10/06 11:44
S12 1	6	S120 and (protect\$3 coat\$3)	US-PGPUB; USPAT	OR	ON	2006/10/06 11:45
S12 2	5	S120 and (passivation)	US-PGPUB; USPAT	OR	ON	2006/10/06 14:14
S12 3	1	"5387314".pn.	US-PGPUB; USPAT	OR	ON	2006/10/06 14:14
S12 4	5	("5308442" "5371531" "5387314" "5402162" "5463412").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/08/17 10:43
S12 5	4	("6412921").URPN.	USPAT	OR	ON	2007/08/17 10:44
S12 6	2	"6412921".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 10:45
S12 7	1	2000-117143.NRAN.	DERWENT	OR	ON	2007/08/17 11:09
S12 8	8	"5308442".pn. ep-401996-\$ did. ep-764533-\$ did. ep-771658-\$ did. ep-401996-\$ did.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:10
S12 9	1	2000-117143.NRAN.	DERWENT	OR	ON	2007/08/17 11:13
S13 0	2	"5317346".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:14
S13 1	2	"5387314".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:14
S13 2	120	((yun with gi with kim).in. (yong with shik with park).in. (sung with joon with park).in.) and samsung.as.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/17 11:47
S13 3	0	(substrate ink chamber heat first second trench uniform (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
S13 4	0	(substrate ink chamber heat first second trench uniform (micron)).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
S13 5	0	(substrate ink chamber heat first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:50
S13 6	2	(substrate ink chamber first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51
S13 7	10	(substrate ink first second trench (micron or ".mu.m" or ".mu.m")).clm.	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51
S13 8	8	S137 not S136	US-PGPUB; USPAT	AND	ON	2007/08/17 11:51